

Organizational Chart

North America

Japan

Europe

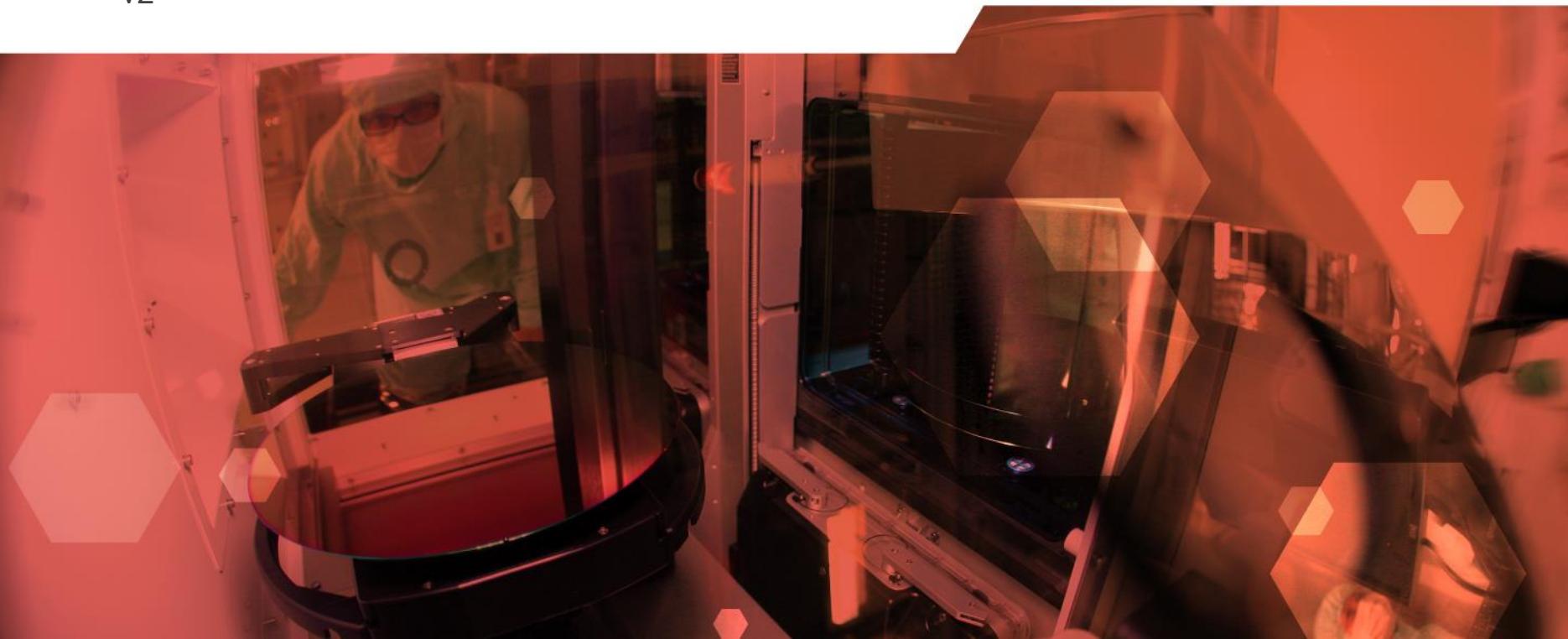
Last Updated: November 2018

v2

Korea

Taiwan

China



Global Technical Committee (GTC) and Technical Committee (TC) Chapters

Global Technical Committee	<u>Locale</u>	China	Europe	Japan	Korea	<u>North</u> <u>America</u>	Taiwan
EH&S				TCC		TCC	TCC
Facilities				TCC	TCC	TCC	
Gases		TCC	TCC			TCC	
Liquid Chemicals		TCC	TCC	TCC		TCC	
FPD Materials & Components				TCC	TCC		
FPD Metrology				TCC	TCC		TCC
MEMS/NEMS						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles).

<u>Global Technical Committee</u>	<u>Locale</u>	China	Europe	Japan	Korea	<u>North America</u>	Taiwan
Traceability				TCC		TCC	
Information & Control			TCC	TCC	TCC	TCC	TCC
Metrics			TCC	TCC		TCC	
Physical Interfaces & Carriers			TCC	TCC		TCC	
Automation Technology			TCC	TCC			TCC
Photovoltaic		TCC		TCC		TCC	TCC
PV Materials		TCC	TCC	TCC		TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles).

* In NA, Micropatterning is traditionally called Microlithography

<u>Global Technical Committee</u>	<u>Locale</u>	China	<u>Europe</u>	Japan	Korea	<u>North America</u>	Taiwan
Micropatterning (Microlithography*)						TCC	
Silicon Wafer			TCC	TCC		TCC	
Compound Semiconductor Materials			TCC	TCC		TCC	
HB-LED	TCC					TCC	
3D Packaging & Integration**				TCC		TCC	TCC
Automated Test Equipment (ATE)						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

* In NA, Micropatterning is traditionally called Microlithography

** 3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017.

Regional Standards Committee (RSC) Organizations

SEMI Europe RSC Organization

Co-Chairs: Bert Planting – ASML, Werner Bergholz – International Standards Consulting
Vice-Chair: Frank Petzold – Trustsec

Europe Chapter of Automation Technology Global Technical Committee

C: Christian Hoffmann – PEER Group

Europe Chapter of Liquid Chemicals Global Technical Committee

C: Jochen Ruth – Pall Corporation

Europe Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Alfred Honold – InReCon
C: Frank Petzold – Trustsec

Europe Chapter of Compound Semiconductor Materials Global Technical Committee

C: Arnd Weber – SiCrystal

Europe Chapter of Information & Control Global Technical Committee

C: Alfred Honold – InReCon
C: Frank Petzold – Trustsec

Europe Chapter of PV Materials Global Technical Committee

C: Peter Wagner – Consultant
C: Christian Hagendorf – Fraunhofer CSP

Europe Chapter of Gases Global Technical Committee

C: Jochen Ruth – Pall Corporation

Europe Chapter of Metrics Global Technical Committee

C: Alfred Honold – InReCon
C: Lothar Pfitzner – FhG IISB

Europe Chapter of Silicon Wafer Global Technical Committee

C: Werner Bergholz – International Standards Consulting
C: Peter Wagner – Consultant
C: Fritz Passek - Siltronic

SEMI Japan RSC Organization

Co-Chairs: Kenji Yamagata – Daifuku, Hidetoshi Sakura – NuFlare Technology

Vice-Chair: Supika Mashiro – TEL

Japan Chapter of 3D Packaging & Integration Global Technical Committee

C: Masahiro Tsuriya – iNEMI
C: Haruo Shimamoto – AIST
C: Kazunori Kato – AiT

Japan Chapter of FPD Materials & Components Global Technical Committee

C: Tadahiro Furukawa – Yamagata University
C: Yoshihiko Shibaura – FUJIFILM

Japan Chapter of PV Materials Global Technical Committee

C: Takashi Ishihara – Mitsubishi Electric
C: Kazuhiko Kashima – Consultant
C: Tetsuo Fukuda – AIST

Japan Chapter of Automation Technology Global Technical Committee

C: Terry Asakawa – Vistaideal Consulting
C: Teruaki Ito – Mitsubishi Electric
C: Fumiya Obuchi – SIEMENS

Japan Chapter of FPD Metrology Global Technical Committee

C: Ryoichi Watanabe – Japan Display
C: Akira Kawaguchi – Otsuka Electronics

Japan Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Tsuyoshi Nagashima – Miraial
C: Kenji Yamagata – DAIFUKU
C: Noriyoshi Toyoda – Hirata Corporation

Japan Chapter of Compound Semiconductor Materials Global Technical Committee

C: Masayoshi Obara – Shin-Etsu Handotai

Japan Chapter of Information & Control Global Technical Committee

C: Takayuki Nishimura – SCREEN
Semiconductor Solutions
C: Mitsuhiro Matsuda – KOKUSAI ELECTRIC

Japan Chapter of Silicon Wafer Global Technical Committee

C: Naoyuki Kawai – Meiji University
C: Tetsuya Nakai – SUMCO

Japan Chapter of Environmental Health & Safety Global Technical Committee

C: Supika Mashiro – TEL
C: Hidetoshi Sakura – NuFlare Technology
C: Moray Crawford – Hatsuta Seisakusho

Japan Chapter of Liquid Chemicals Global Technical Committee

C: Hiroshi Tomita – Toshiba Memory
C: Hiroyuki Araki – SCREEN Semiconductor
Solutions

Japan Chapter of Traceability Global Technical Committee

C: Yoichi Iga – Toshiba
C: Hirokazu Tsunobuchi – Keyence

Japan Chapter of Facilities Global Technical Committee

C: Hiromichi Enami – Hitachi High-Technologies
C: Isao Suzuki – Consultant

Japan Chapter of Metrics Global Technical Committee

C: Mitsune Sakamoto – ZAMA Consulting

Special Groups Reporting to the JRSC

Japan Chapter of Gases Global Technical Committee

C: Hiromichi Enami – Hitachi High-Technologies
C: Isao Suzuki – Consultant

Japan Chapter of Photovoltaic Global Technical Committee

C: Kazuhiko Kashima – Consultant
C: Masaaki Yamamichi – RTS Corporation

Standardization Process Improvement (SPI)

L: Supika Mashiro – TEL

SEMI North America (NA) RSC Organization – NA Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimetrix

NA Chapter of 3D Packaging & Integration Global Technical Committee

C: Richard Allen – NIST
C: Sesh Ramaswami – Applied Materials
C: Chris Moore – Covalent Metrology

NA Chapter of HB-LED Global Technical Committee

C: Mike Feng – Silian
C: Chris Moore – Covalent Metrology
C: Andrew Kim – InnovationforX

NA Chapter of Photovoltaic Global Technical Committee

C: Win Baylies – BayTech-Resor
C: James Moyne – AMAT/University of Michigan

NA Chapter of Automated Test Equipment Global Technical Committee

C: Ajay Khoche – Khoche Consulting

NA Chapter of Information & Control Global Technical Committee

C: Jack Ghiselli – Ghiselli Consulting
C: Brian Rubow – Cimetrix
C: James Moyne – AMAT / University of Michigan

NA Chapter of PV Materials Global Technical Committee

C: Hugh Gotts – Air Liquide

NA Chapter of Compound Semiconductor Materials Global Technical Committee

C: Russ Kremer – Freiberger Compound
Materials
C: James Oliver – Northrop Grumman

NA Chapter of Liquid Chemicals Global Technical Committee

C: Don Hadder – Intel
C: Steve Rogers – KMG Chemicals
C: Laura Ledebach – PeroxyChem
C: Koh Murai – Mega Fluid Systems

NA Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Matt Fuller – Entegris
C: Melvin Jung – Intel

NA Chapter of Environmental Health & Safety Global Technical Committee

C: Chris Evanston – Salus Engineering
C: Sean Larsen – Lam Research
C: Bert Planting – ASML

NA Chapter of MEMS/NEMS Global Technical Committee

C: Steve Martell – NSONOSCAN
C: Win Baylies – BayTech-Resor

NA Chapter of Silicon Wafer Global Technical Committee

C: Dinesh Gupta – STA
C: Noel Poduje – SMS
VC: Mike Goldstein

NA Chapter of Facilities Global Technical Committee

C: Steve Lewis – BW Design Group

NA Chapter of Metrics Global Technical Committee

C: David Bouldin – Fab Consulting
C: Mark Frankfurth – Cymer
C: Vladimir Kraz – BestESD

NA Chapter of Traceability Global Technical Committee

C: Win Baylies – BayTech-Resor
C: Yaw Obeng – NIST

NA Chapter of Gases Global Technical Committee

C: Mohamed Saleem – Brooks Instrument

NA Chapter of Microlithography Global Technical Committee

C: Bryan Barnes – NIST

NA RSC Technical Architect Board

C: James Moyne – AMAT /
University of Michigan
C: Yaw Obeng – NIST

SEMI North America RSC Organization – China Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimetrix

**China Chapter of Photovoltaic
Global Technical Committee**

C: Guangchun Zhang – CanadianSolar
C: Jun Liu – China Electronics Standardization Institute

**China Chapter of PV Materials
Global Technical Committee**

C: Guangchun Zhang – CanadianSolar
C: Jun Liu – China Electronics Standardization Institute

**China Chapter of HB-LED
Global Technical Committee**

C: Hongbo Zuo – AURORA
C: Jiangbo Wang – HC SemiTek

SEMI North America RSC Organization – Korea Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimetrix

Korea Chapter of Facilities
Global Technical Committee
C: Kwang Sun Kim – KUT

Korea Chapter of FPD Metrology
Global Technical Committee

C: Jongho Chong – Samsung Display
C: Kyungjin Kang – LG Electronics

Korea Chapter of FPD Materials & Components
Global Technical Committee
C: Jongseo Lee – Dell
C: Il-Ho (William) Kim – Light Measurement Solution

Korea Chapter of Information & Control
Global Technical Committee

C: Hyungsu Kim – Doople
C: Chul Hong Ahn – SK hynix
C: Gun Woo Lee – Lam Research

SEMI North America RSC Organization – Taiwan Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimetrix

Taiwan Chapter of 3D Packaging & Integration

Global Technical Committee

C: Wendy Chen – King Yuan Electronics

C: Chien-Chung Lin – ITRI

C: Roger Hwang – ASE

Taiwan Chapter of Flat Panel Display

Global Technical Committee

C: Mike Yao – CMS/ITRI

C: Jia-Ming Liu – TDMDA

Taiwan Chapter of Automation Technology

Global Technical Committee

C: K.C. Chou – ASE

C: Jen-Hui Tsai – ITRI

C: Gwo-Sheng Peng – ITRI/CMS

C: Yung-Mao Zheng – MIRDC

Taiwan Chapter of Information & Control

Global Technical Committee

C: Robert Chien – TSMC

Taiwan Chapter of Environmental Health & Safety

Global Technical Committee

C: Shuh-Woei Yu – SAHTECH

C: Fang-Ming Hsu – TSMC

Taiwan Chapter of Photovoltaic

Global Technical Committee

C: T.C. Wu – CMS/ITRI

C: J.S. Chen – TeraSolar

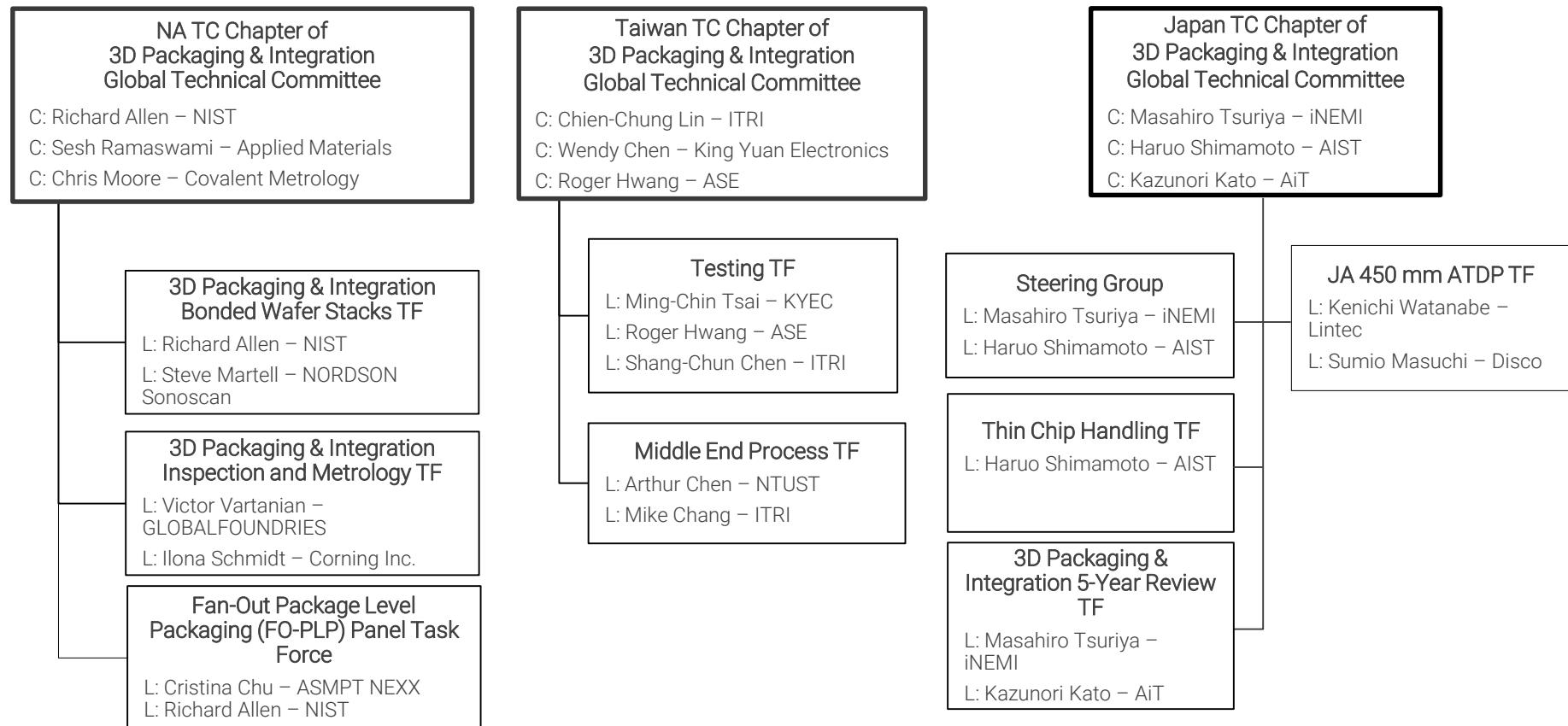
C: Ray Sung – UL Taiwan

ISC Taiwan Advisor

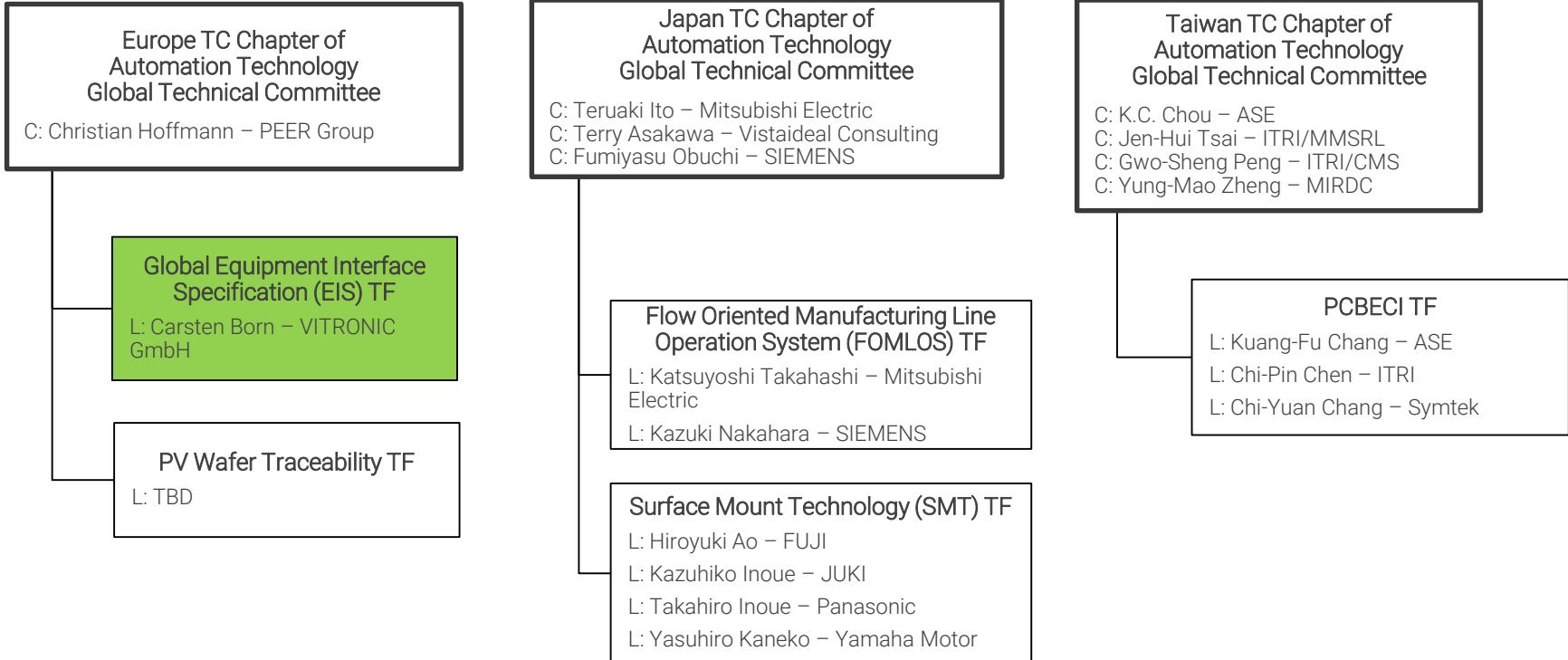
Tzeng-Yow Lin – CMS/ITRI

Organization of Each TC Chapter

3D Packaging & Integration (3DP&I) Global Technical Committee

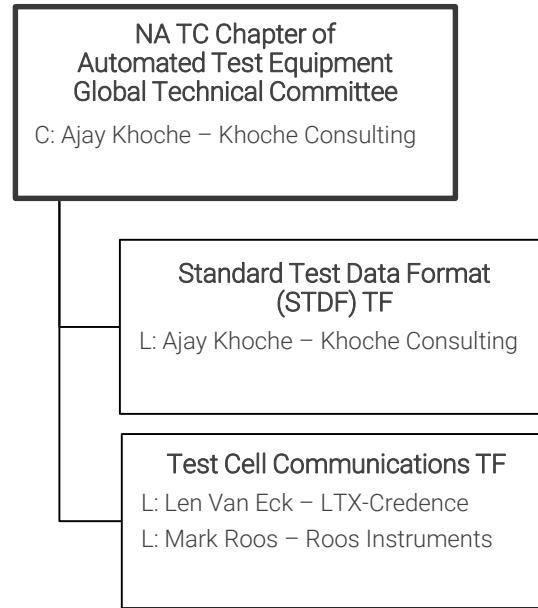


Automation Technology (AT) Global Technical Committee

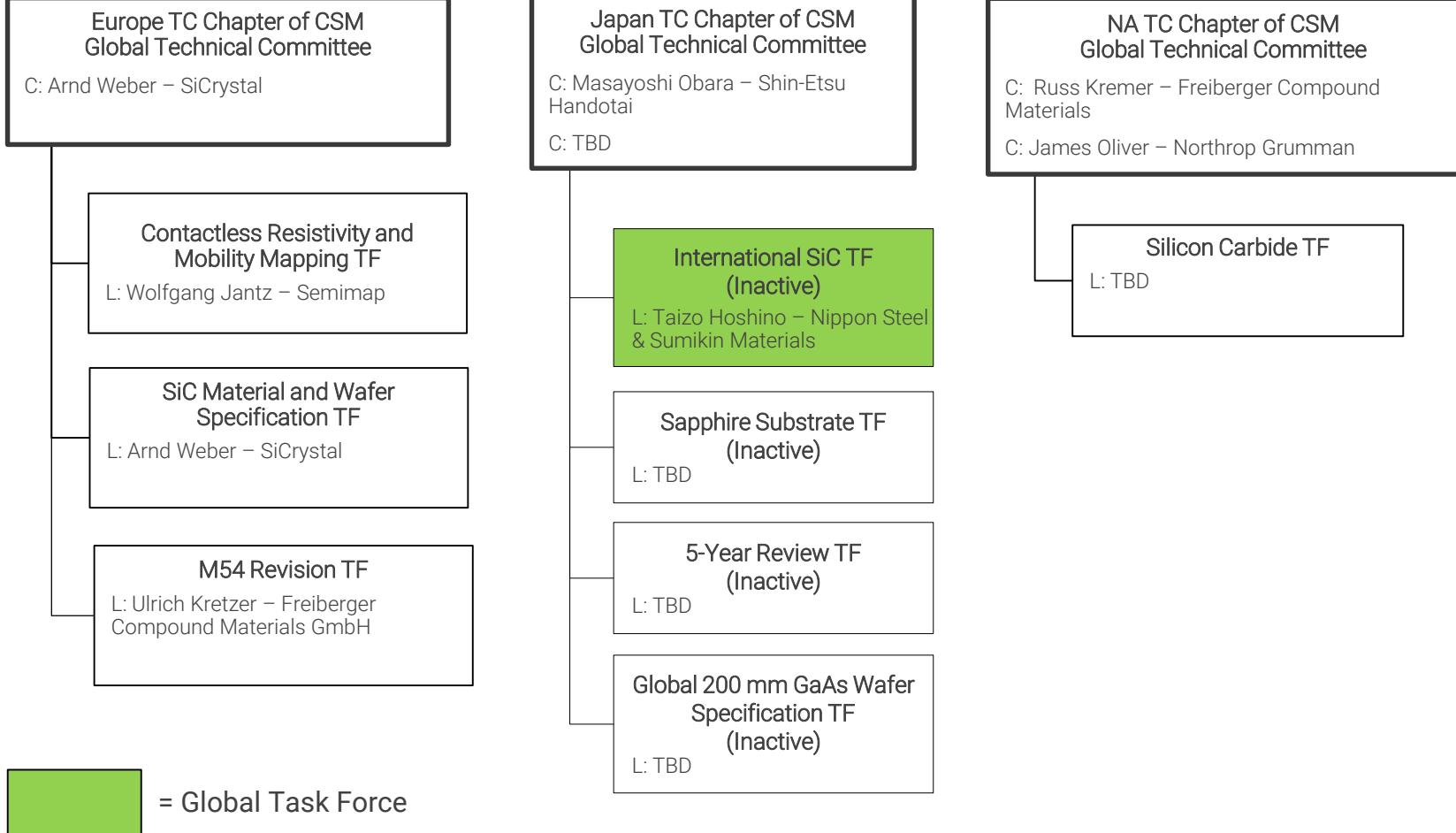


= Global Task Force

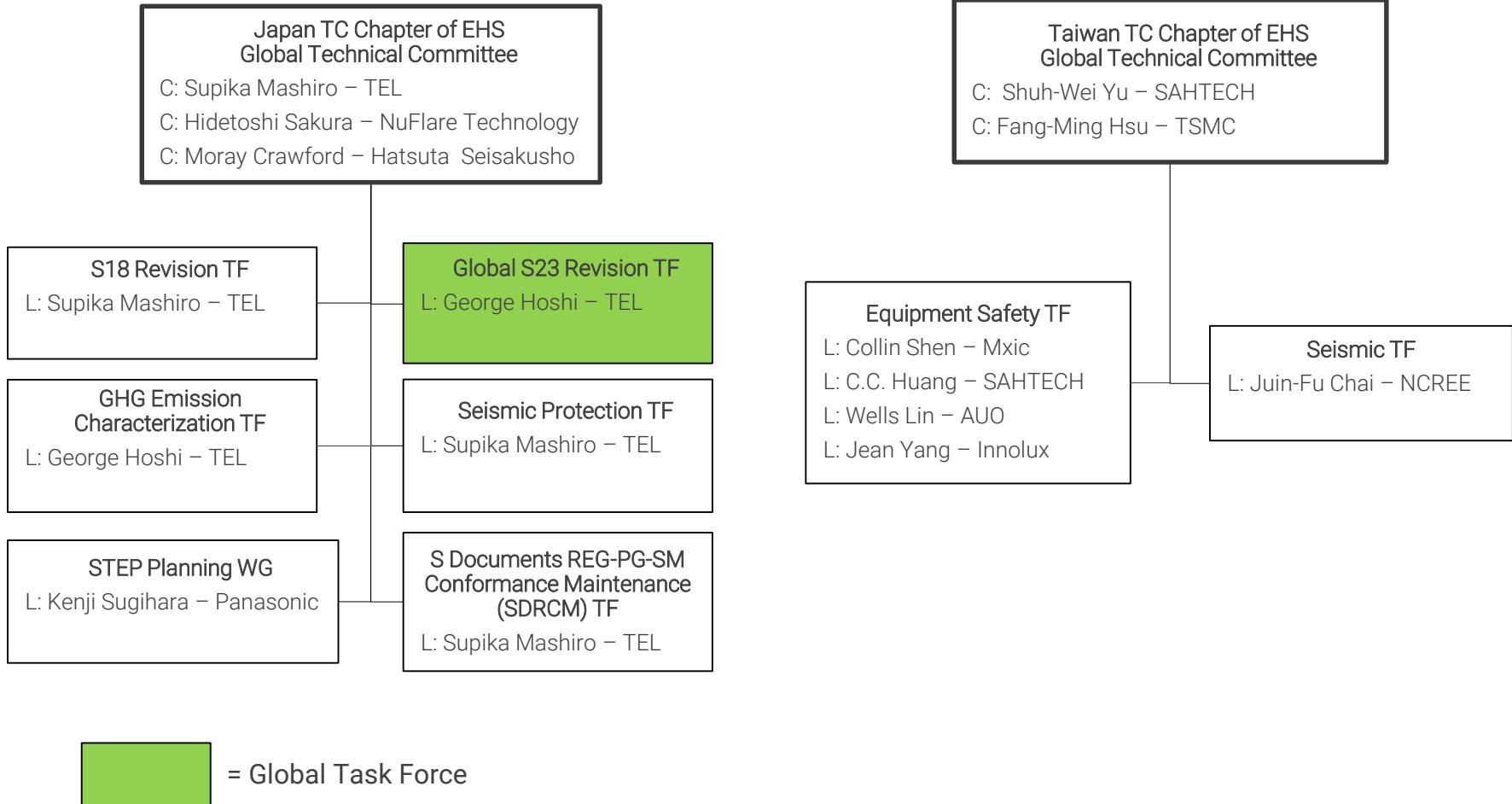
Automated Test Equipment (ATE) Global Technical Committee



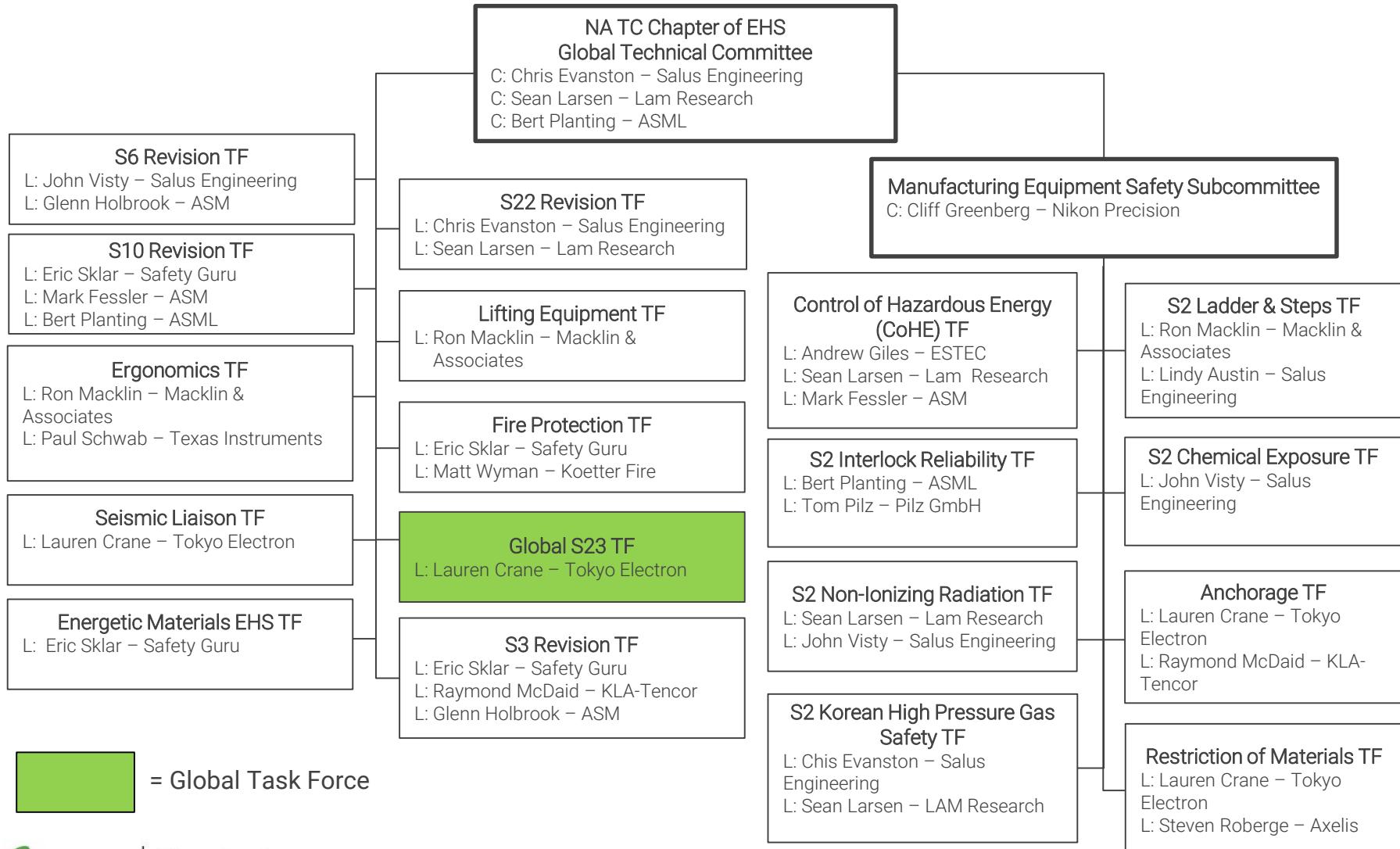
Compound Semiconductor Materials (CSM) Global Technical Committee



Environmental, Health & Safety (EH&S) Global Technical Committee



Environmental, Health & Safety (EH&S) Global Technical Committee



Facilities Global Technical Committee

Japan TC Chapter of Facilities Global Technical Committee

C: Hiromichi Enami – Hitachi High Technologies
C: Isao Suzuki – Consultant

F1 Revision TF

L: Masafumi Kitano – Fujikin

5-Year Review TF

L: Masafumi Kitano – Fujikin

Korea TC Chapter of Facilities Global Technical Committee

C: Kwang Sun Kim – KUT

Equipment Cleanliness TF

L: TBD

NA TC Chapter of Facilities Global Technical Committee

C: Steve Lewis – BW Design Group

F51 Revision TF

L: Dalia Vernikovsky – Applied Seals North America

Building Information Modeling (BIM) for Semiconductor Capital Equipment TF

L: Ben Bruce – Applied Materials

Power Grid Harmonics TF

L: Alex McEachern – Power Standards Lab

FPD Metrology Global Technical Committee

Japan TC Chapter of FPD Metrology Global Technical Committee

C: Ryoichi Watanabe – Japan Display
C: Akira Kawaguchi – Otsuka Electronics

Korea TC Chapter of FPD Metrology Global Technical Committee

C: Jongho Chong – Samsung Display
C: Kyungjin Kang – LG Electronics

Taiwan TC Chapter of FPD Metrology Global Technical Committee

C: Mike Yao – CMS/ITRI
C: Jia-Ming Liu – TDMDA

Perceptual Viewing Angle TF

L: Myongyoung Lee – LG Electronics

Perceptual Image Quality TF

L: Jongho Chong – Samsung
Display

Flexible Display TF

L: Chao-Hua Wen – ITRI

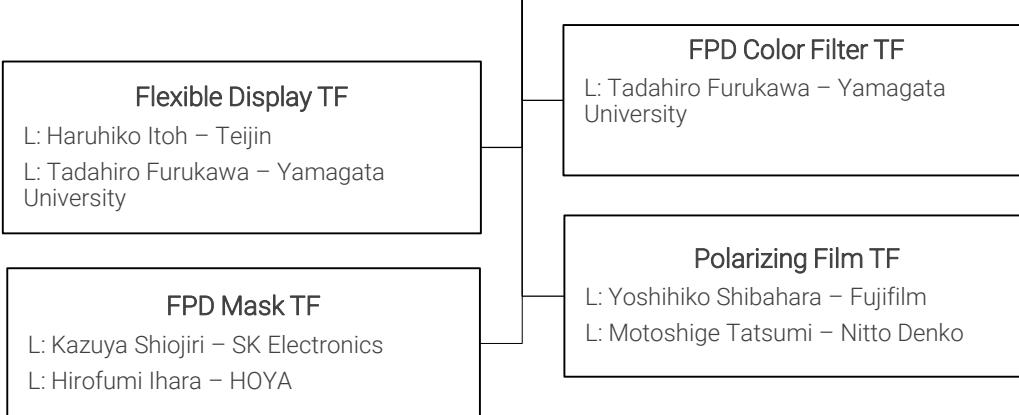
Transparent Display TF

L: Pei-Li Sun – NTUST
L: Justic Lin – Acer

FPD Materials & Components Global Technical Committee

Japan TC Chapter of FPD Materials & Components
Global Technical Committee
C: Tadahiro Furukawa – Yamagata University
C: Yoshihiko Shibahara – Fujifilm

Korea TC Chapter of FPD Materials & Components
Global Technical Committee
C: Jongseo Lee – Dell
C: Il-Ho (William) Kim – Light Measurement Solution



Gases

Global Technical Committee

Europe TC Chapter of Gases
Global Technical Committee

C: Jochen Ruth – Pall Corporation

Japan TC Chapter of Gases
Global Technical Committee

C: Hiromichi Enami – Hitachi High
Technologies

C: Isao Suzuki – Consultant

NA TC Chapter of Gases
Global Technical Committee

C: Mohamed Saleem – Brooks
Instrument

Permeation Tubes for Trace
Moisture Calibration TF

L: Jean-Marie Collard – Solvay
Chemicals

L: Jim McKinley – KIN-TEK

Cleaning Gases TF

L: Jean-Marie Collard – Solvay
Chemicals

Filters & Purifiers TF

L: Mohamed Saleem – Brooks
Instrument

L: Yanli Chen – UCT

Heater Jacket TF

L: Matt Milburn – UCT

L: David Colquhoun –
BriskHeat

Mass Flow Controller TF

L: Mohamed Saleem –
Brooks Instrument

L: Erica Kitano – Fujikin

Materials of Construction Gas
Delivery Systems TF

L: Bill Kiikvee – AP Tech

Pressure Measurement TF
(Inactive)

L: Yanli Chen – UCT

L: Jeff Christian – WIKA

Surface Mount Sandwich
Component Dimensions TF
(Inactive)

L: Matt Milburn – UCT

Gases Specification TF

L: Mohamed Saleem –
Brooks Instrument

L: Thomas Fritz – WIKA

HB-LED Global Technical Committee

China TC Chapter of HB-LED Global Technical Committee

C: Hongbo Zuo – AURORA
C: Jiangbo Wang – HC SemiTek

Single Crystal Sapphire TF

L: Yong Ji – Guizhou Haotian Optoelectronics Technology
L: Xinhong Yang – AURORA

Sapphire Single Crystal Ingot TF

L: Hongbo Zuo – AURORA

GaN based LED Epitaxial Wafer TF

L: Jiangbo Wang – HC SemiTek

Sapphire Single Crystal Orientation TF (Inactive)

L: Songbin Zhao – DDXDF

Patterned Sapphire Substrate TF

L: Jianzhe Liu – ECBO

HB-LED Equipment Communication Interface TF

L: Steven Lee – AMEC
L: Edward Lee – AMEC

NA TC Chapter of HB-LED Global Technical Committee

C: Mike Feng – Silian
C: Chris Moore – Covalent Metrology
C: Andrew Kim – InnovationforX

Patterned Sapphire Substrate (PSS) TF

L: Win Baylies – BayTech-Resor

HB-LED Equipment Communication Interfaces TF (Inactive)

L: Brian Rubow – Cimetrix

HB-LED Equipment Automation Interfaces TF (Inactive)

L: Daniel Babbs – Brooks Automation
L: Jeff Felipe – Entegris

Test Methods TF (Inactive)

L: Peter Wagner – Self

HB-LED Wafer TF

L: Win Baylies – BayTech-Resor

HB-LED Impurities & Defects in Sapphire Wafers TF (Inactive)

L: Luke Glinski – GT Advanced Technologies

HB-LED Source Materials TF (Korea)

L: Paul Ahn – Veeco
L: H.B. Joo – Aixtron
L: Sungjin Jun – LG Innotek
L: Deok-gil – Samsung Electronics

Information & Control (I&C) Global Technical Committee

Europe TC Chapter of Information & Control Global Technical Committee

C: Alfred Honold – InReCon
C: Frank Petzold – Trustsec

Process Control Systems TF

L: Martin Schellenberger – FhG
IISB

Japan TC Chapter of Information & Control Global Technical Committee

C: Takayuki Nishimura – SCREEN Semiconductor Solutions
C: Mitsuhiro Matsuda – KOKUSAI ELECTRIC
TA: Tadashi Mochizuki – TEL
Adviser: Mitch Sakamoto – Zama Consulting

GEM300 TF

L: Yuko Toyoshima – Hitachi High Technologies
L: Masaya Nagata – TEL

Japan I&CC Maintenance TF

L: Mitsuhiro Matsuda – KOKUSAI ELECTRIC

Sensor Bus TF

L: Hideaki Ogihara – NaigaiTEC
L: Tadashi Somei – Pionics
L: Hajime Miura – Techno-Holon

Equipment Data Acquisition (EDA) WG

L: Mitch Sakamoto – ZAMA Consulting
L: Takashi Nakagawa – Yokogawa Solution Service

Diagnostic Data Acquisition (DDA) TF

L: Mitch Sakamoto – ZAMA Consulting
L: Takashi Nakagawa – Yokogawa Solution Service

Fab & Equipment Information Security TF

L: Tadashi Mochizuki – Tokyo Electron

Korea TC Chapter of Information & Control Global Technical Committee

C: Hyungsu Kim – Doople
C: Chul Hong Ahn – SK hynix
C: Gun Woo Lee – Lam Research

GEM300 TF

L: Jong Sub Shim – ASM
L: Chang Yul Cho – SEMES
L: Byoung Min Im – TEL Korea

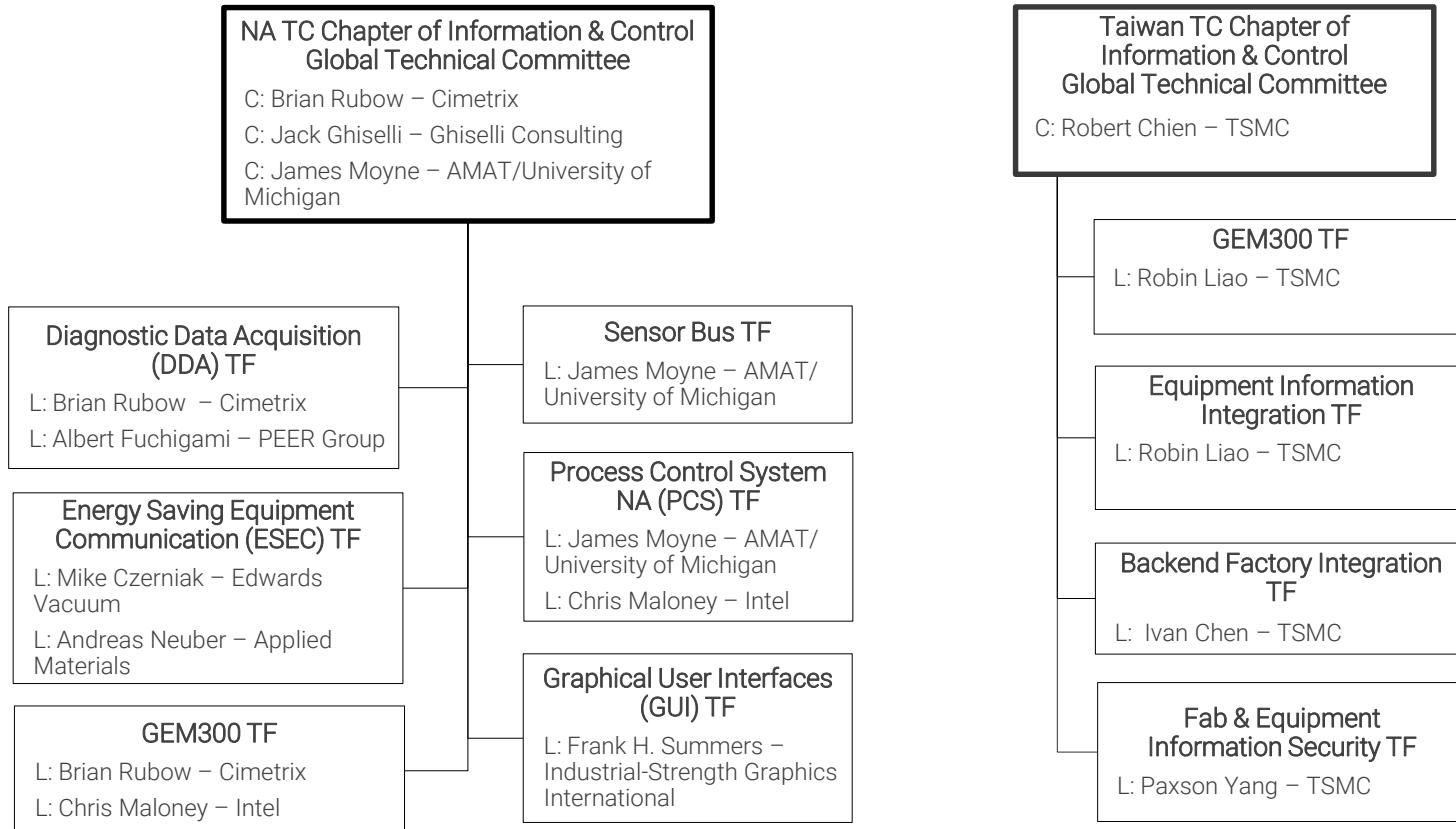
Diagnostic Data Acquisition (DDA) TF

L: Hyungsu Kim – Doople

Advanced Back-End Factory Integration (ABFI) TF

L: Y.S. Lim – Miracom Inc.

Information & Control (I&C) Global Technical Committee



Liquid Chemicals Global Technical Committee

Europe TC Chapter of Liquid Chemicals Global Technical Committee

C: Jochen Ruth – Pall Corporation

Precursor Specifications TF
L: Paul Williams – SAFC Hitech

Solvents in Advanced
Processes TF
L: TBD

Japan TC Chapter of Liquid Chemicals Global Technical Committee

C: Hiroshi Tomita – Toshiba Memory
C: Hiroyuki Araki – SCREEN
Semiconductor Solutions

Liquid Filter TF

L: Takuya Nagafuchi – Nihon
Entegris
L: Takehito Mizuno – Nihon Pall

Liquid-Borne Particle Counter TF

L: Kaoru Kondo – RION
L: Kazutoshi Kato – PMS
Division/Spectris Co., Ltd.

Diaphragm Valve TF

L: Shigeru Ohsugi – CKD
L: Kimihito Sasao – Advance
Electric

Welding Fitting TF

L: Kimihito Sasao – Advance
Electric
L: Takashi Hasegawa – KITZ SCT

Ultrapure Liquid Evaluation Study Group

L: Kaoru Kondo – RION
L: Hiroshi Sugawara – ORGANO

NA TC Chapter of Liquid Chemicals Global Technical Committee

C: Don Hadder – Intel
C: Steve Rogers – KMG Chemicals
C: Laura Ledebach – PeroxyChem

Chemical Analytical Methods (CAM) TF

L: Don Hadder – Intel
L: David Kandiyeli – Mega Fluid
Systems

High Purity Liquid Assemblies & Systems TF

L: Koh Murai – Mega Fluid
Systems
L: David Kandiyeli – Mega Fluid
Systems

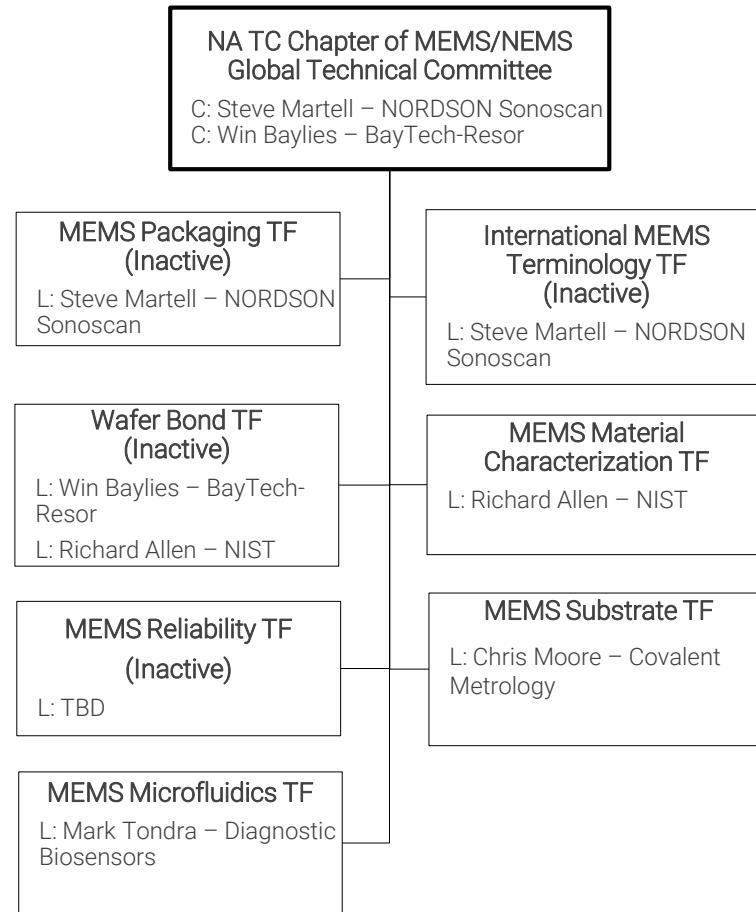
High Purity Polymer Materials & Components TF

L: Bob McIntosh – GF Piping

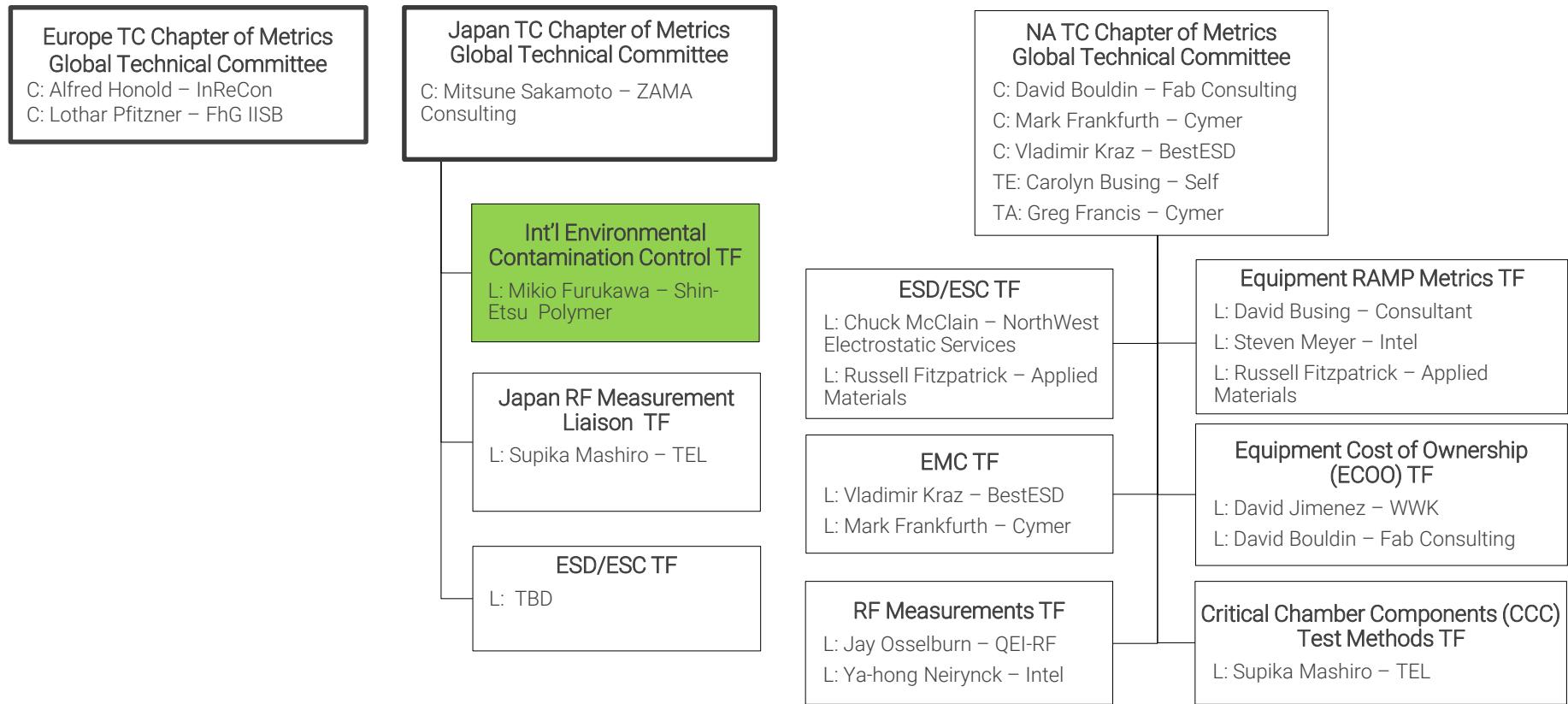
Ultra Pure Water (UPW) TF

L: Slava Libman – FTD Solutions
L: Bob McIntosh – GF Piping

MEMS/NEMS Global Technical Committee

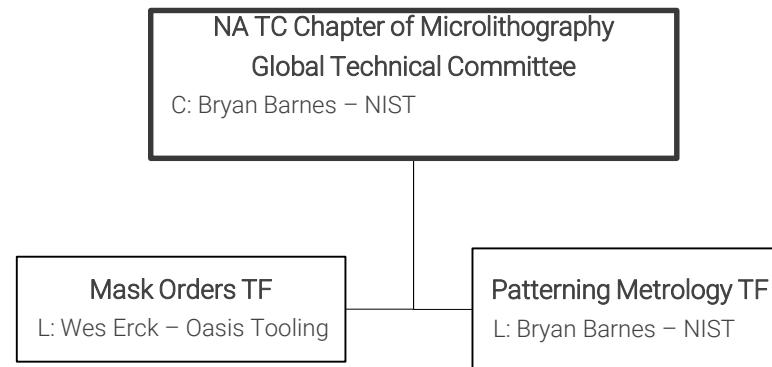


Metrics Global Technical Committee

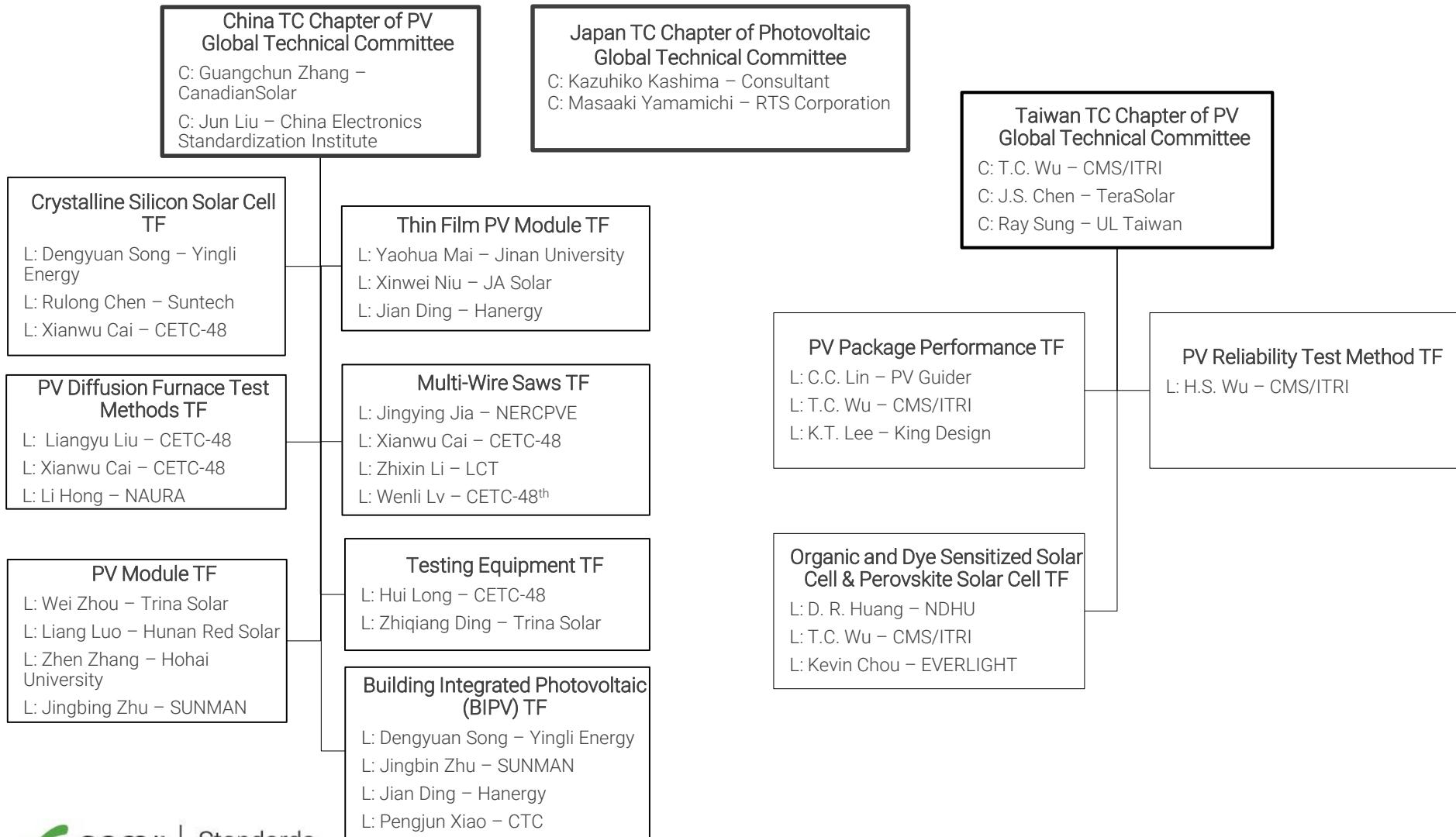


= Global Task Force

Micropatterning Global Technical Committee



Photovoltaic (PV) Global Technical Committee



PV Materials Global Technical Committee

China TC Chapter of PV Materials Global Technical Committee

C: Guangchun Zhang – CanadianSolar
C: Jun Liu – China Electronics Standardization Institute

PV Silicon Raw Materials TF

L: Lu Wenfeng – GCL
L: Dongxu Chu – SINOSICO
L: Li He – CPVT

PV Silicon Wafer TF

L: Yuepeng Wan – GCL
L: Liangping Deng – LONGi
L: Jingang Lu – HI-TECH

Europe TC Chapter of PV Materials Global Technical Committee

C: Peter Wagner – Consultant
C: Christian Hagendorf – FhG-CSP

Int'l PV Analytical Test Methods, Metrology, and Inspection TF

L: TBD

PV Silicon Materials TF

L: Peter Wagner – Consultant

PV Material Degradation TF

L: Max Koentopp – Hanwha Q-cells
L: Christian Hagendorf – FhG-CSP

Japan TC Chapter of PV Materials Global Technical Committee

C: Takashi Ishihara – Mitsubishi Electric
C: Kazuhiko Kashima – Consultant
C: Tetsuo Fukuda – AIST

Japan PV Materials TF

L: Tetsuo Fukuda – AIST
L: Takashi Ishihara – Mitsubishi Electric

NA TC Chapter of PV Materials Global Technical Committee

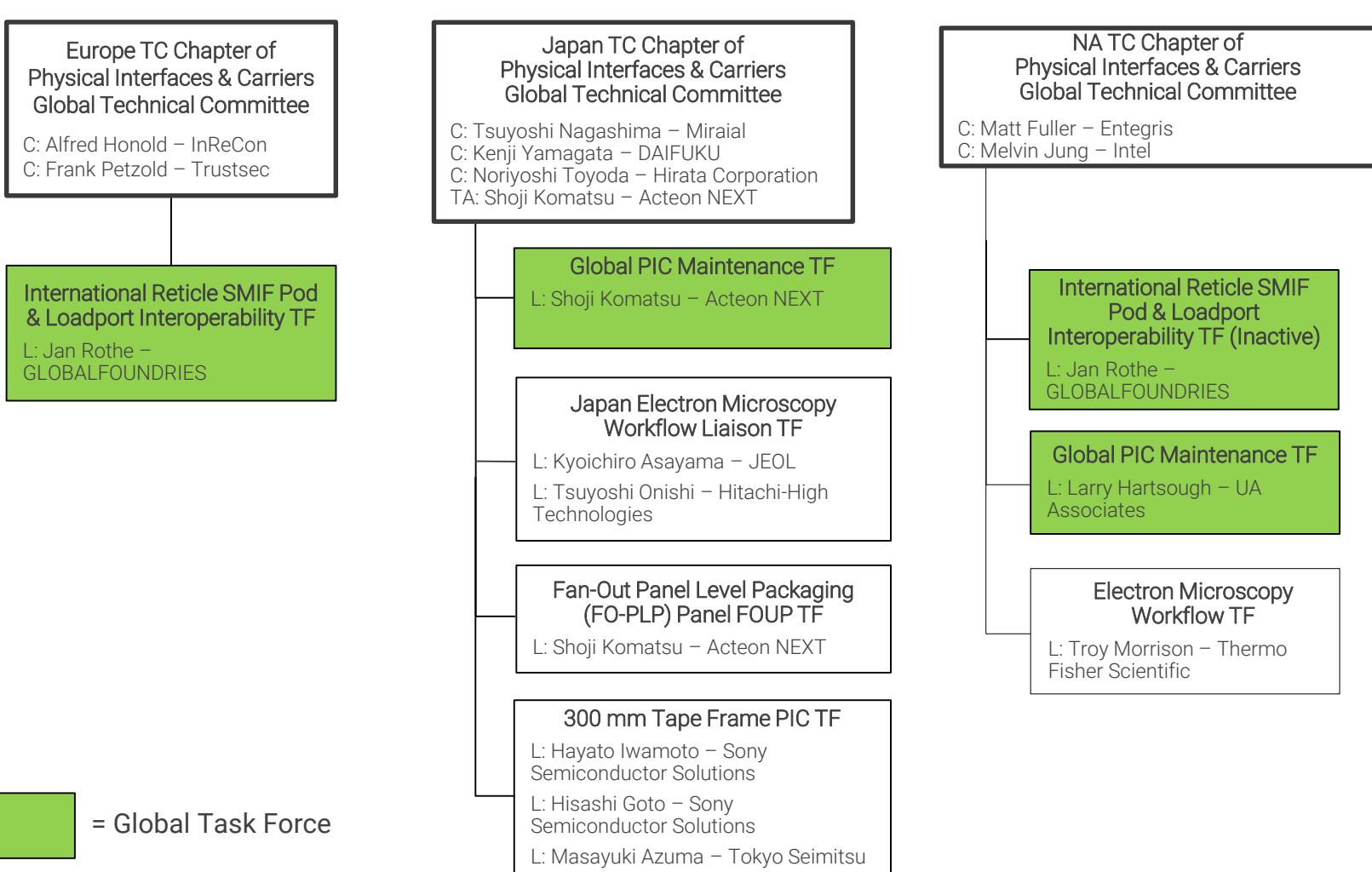
C: Hugh Gotts – Air Liquide Electronics US

Int'l PV Analytical Test Methods, Metrology, and Inspection TF

L: Hugh Gotts – Air Liquide Electronics US
L: Chris Moore – Covalent Metrology

= Global Task Force

Physical Interfaces & Carriers (PIC) Global Technical Committee



Silicon Wafer Global Technical Committee

Europe TC Chapter of Silicon Wafer Global Technical Committee

C: Werner Bergholz – Jacobs University of Bremen
C: Peter Wagner – Consultant
C: Fritz Passek – Siltronic

International Advanced Surface Inspection TF

L: Frank Riedel – Siltronic

International Advanced Wafer Geometry TF

L: Fritz Passek – Siltronic
L: Frank Riedel – Siltronic

International Terminology TF

L: Peter Wagner – Consultant

International Test Methods TF

L: Peter Wagner – Consultant

International Polished Wafers TF

L: Frank Riedel – Siltronic

NA TC Chapter of Silicon Wafer Global Technical Committee

C: Dinesh Gupta – STA
C: Noel Poduje – SMS

International Annealed Wafers TF

L: Dinesh Gupta – STA

International Terminology TF

L: TBD

International Epitaxial Wafers TF

L: Dinesh Gupta – STA

International Test Methods TF

L: Dinesh Gupta – STA

International Polished Wafers TF

L: John Valley – Nanometrics

International Advanced Wafer Geometry TF

L: Noel Poduje – SMS

International SOI Wafers TF

L: Gerd Pfeifter – GLOBALFOUNDRIES

International Automated Advance Surface Inspection TF

L: Kurt Haller – KLA-Tencor

= Global Task Force

Silicon Wafer Global Technical Committee

International Terminology TF
L: Tetsuya Nakai – SUMCO

International SOI Wafers TF
L: Atsushi Ogura – Meiji University
L: Tetsuya Nakai – SUMCO

International Polished Wafers TF
L: Yasutoshi Takamoti – GlobalWafers Japan

International Annealed Wafers TF
L: Koji Araki – GlobalWafers Japan

International Epitaxial Wafers TF
L: Naohisa Toda – Shin-Etsu Handotai

Japan TC Chapter of Silicon Wafer Global Technical Committee

C: Naoyuki Kawai – Meiji University
C: Tetsuya Nakai – SUMCO

International Test Method TF
L: Ryuji Takeda – GlobalWafers Japan

Japan Test Method TF
L: Ryuji Takeda – GlobalWafers Japan
L: Tsuyoshi Otsuki – Shin-Etsu Handotai
L: Mikako Omata – SCAS

Surface Metal Chemical Analysis WG
L: Ryuji Takeda – GlobalWafers Japan
L: Ryo Machida – SCAS

Bulk Heavy Metal Analysis by Electrical Measurement WG
L: Shingo Sumie – KOBELCO
L: Masaru Akamatsu – KOBELCO

GOI WG
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Surface Organic Contaminant Analysis WG
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BMD DZ WG
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JA Shipping Box

L: Shoji Komatsu – Acteon NEXT
L: Tsuyoshi Nagashima – Miraial

International 450 mm Shipping Box TF

L: Shoji Komatsu – Acteon NEXT

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L: Satoshi Akiyama – Raytex Optima

Japan JWG TF

L: Masanori Yoshise – Wafer Information Service
L: Satoshi Akiyama – Raytex Optima

International Advanced Surface Inspection TF

L: Masami Ikota – Hitachi-High Technologies

= Global Task Force

Traceability Global Technical Committee

